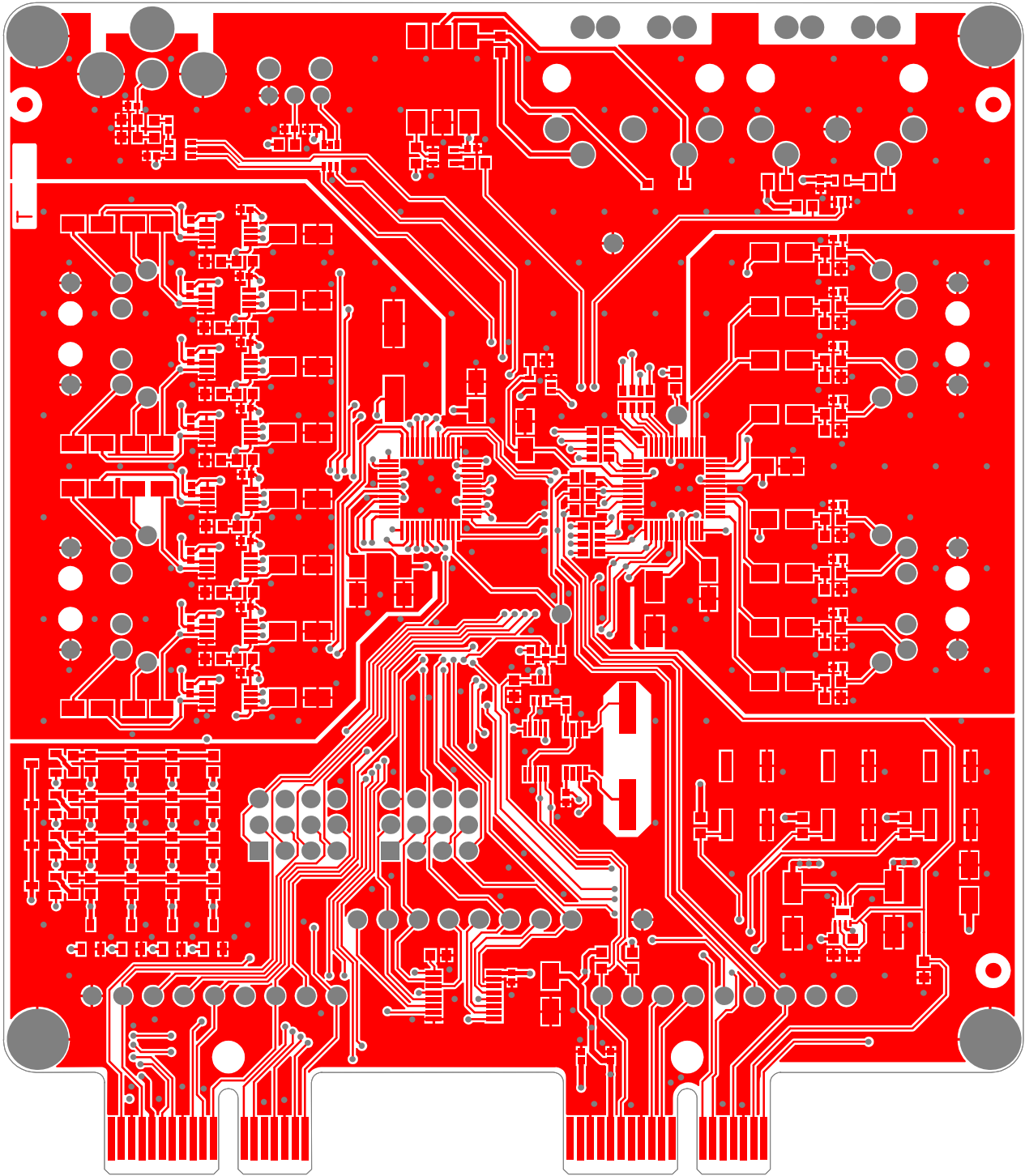


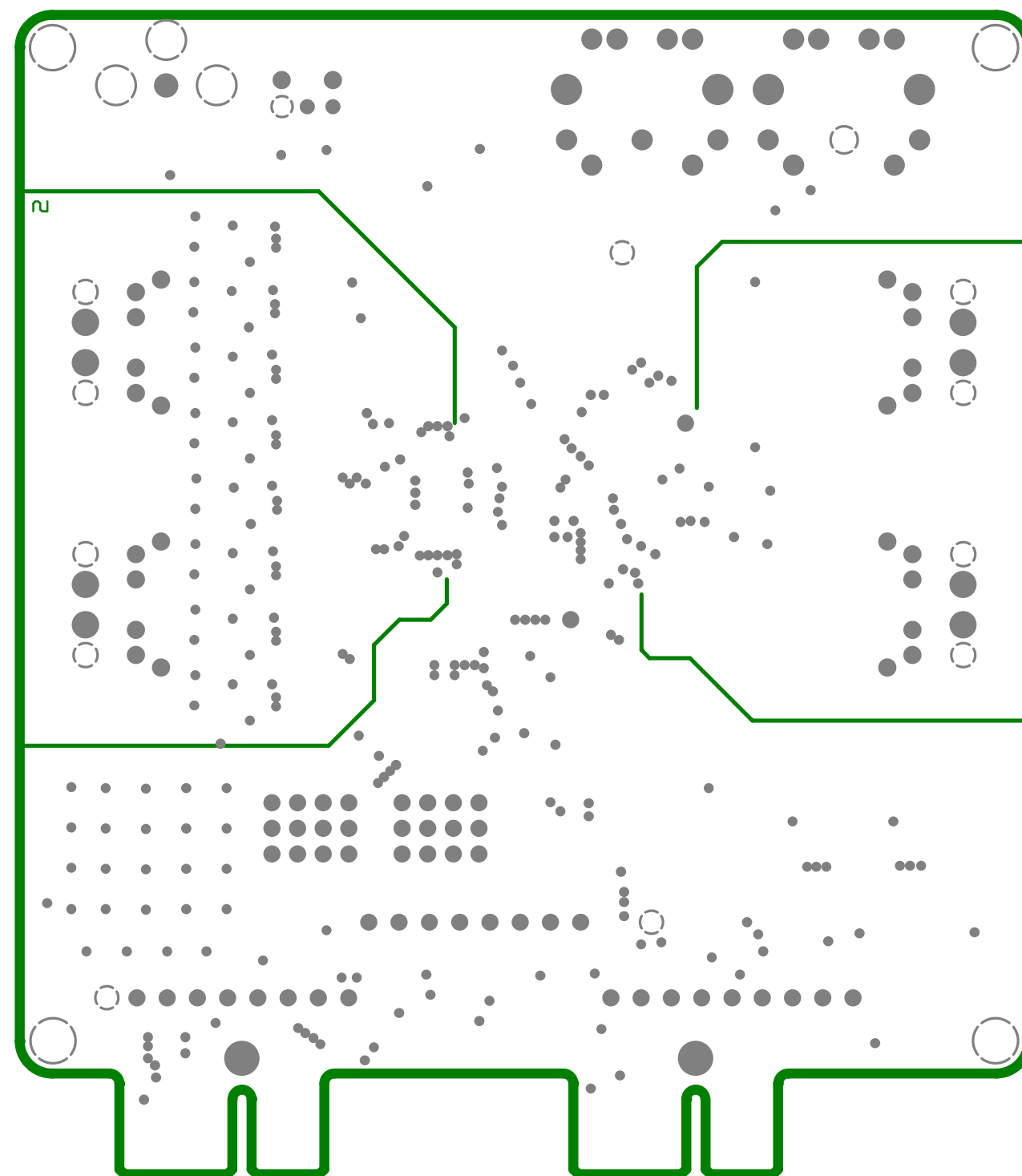
Top Copper



XMOS LTD = XA-SK-AUDIO8 = 1V2A = 19 MAR 2014

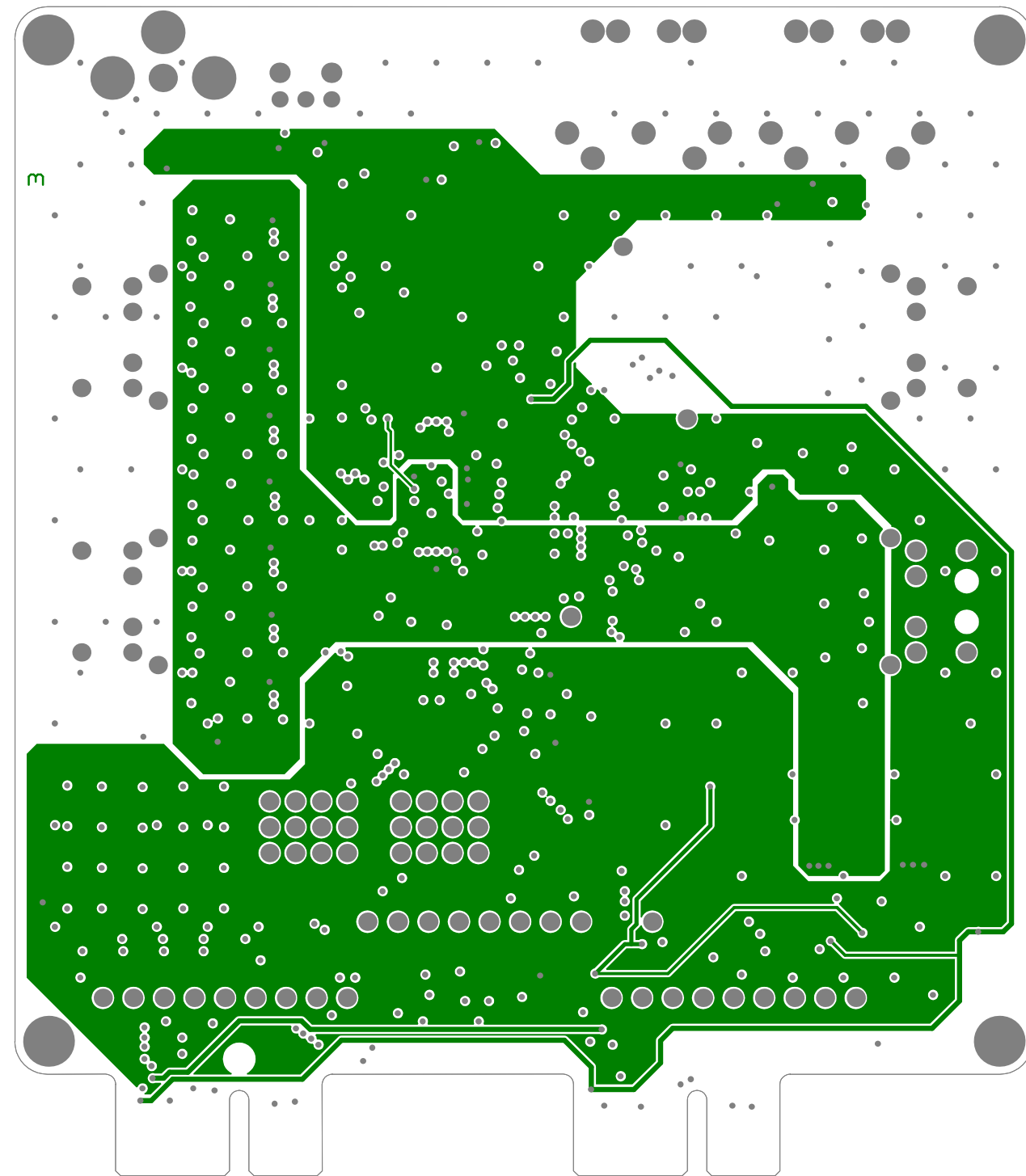
TOP COPPER LAYER

Inner 1



INNER 1 COPPER LAYER

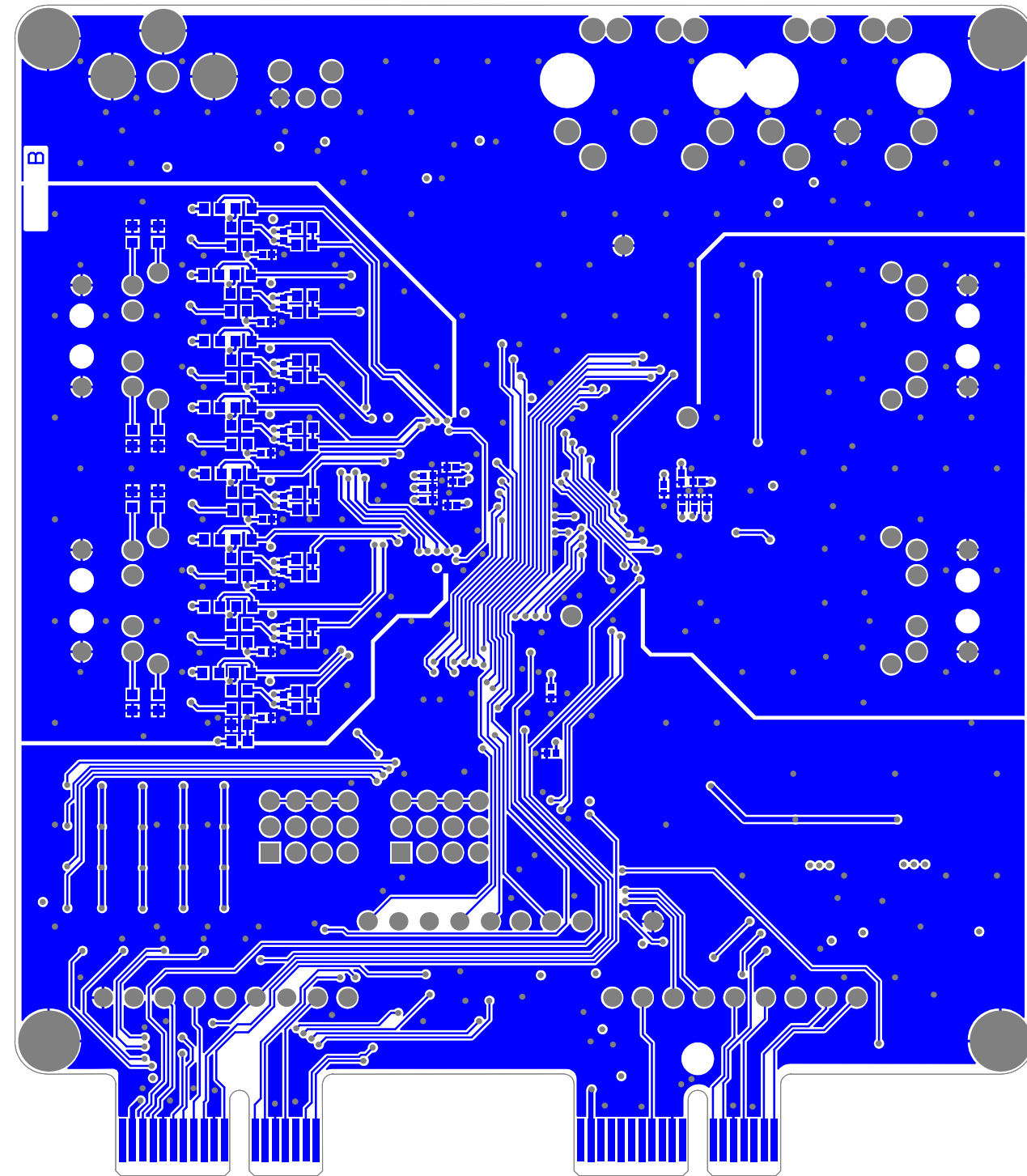
Inner 2



XMOS LTD = XA-SK-AUDIO8 = 1V2A = 19 MAR 2014

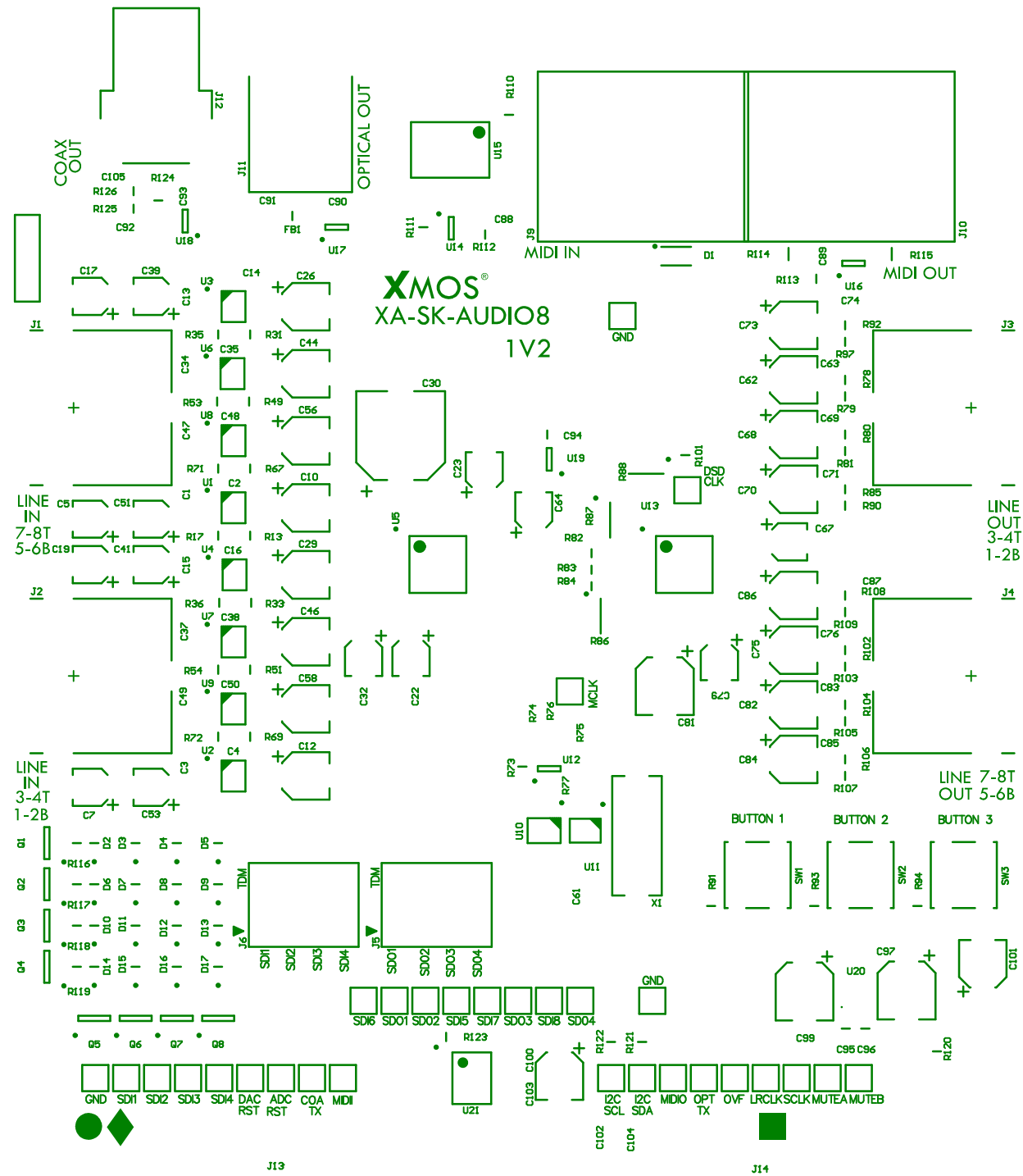
INNER 2 COPPER LAYER

Bottom Copper



XMOS LTD = XA-SK-AUDIO8 = 1V2A = 19 MAR 2014

BOTTOM COPPER LAYER



TOP SILKSCREEN LAYER



445
255

535
80

745
635

835
115

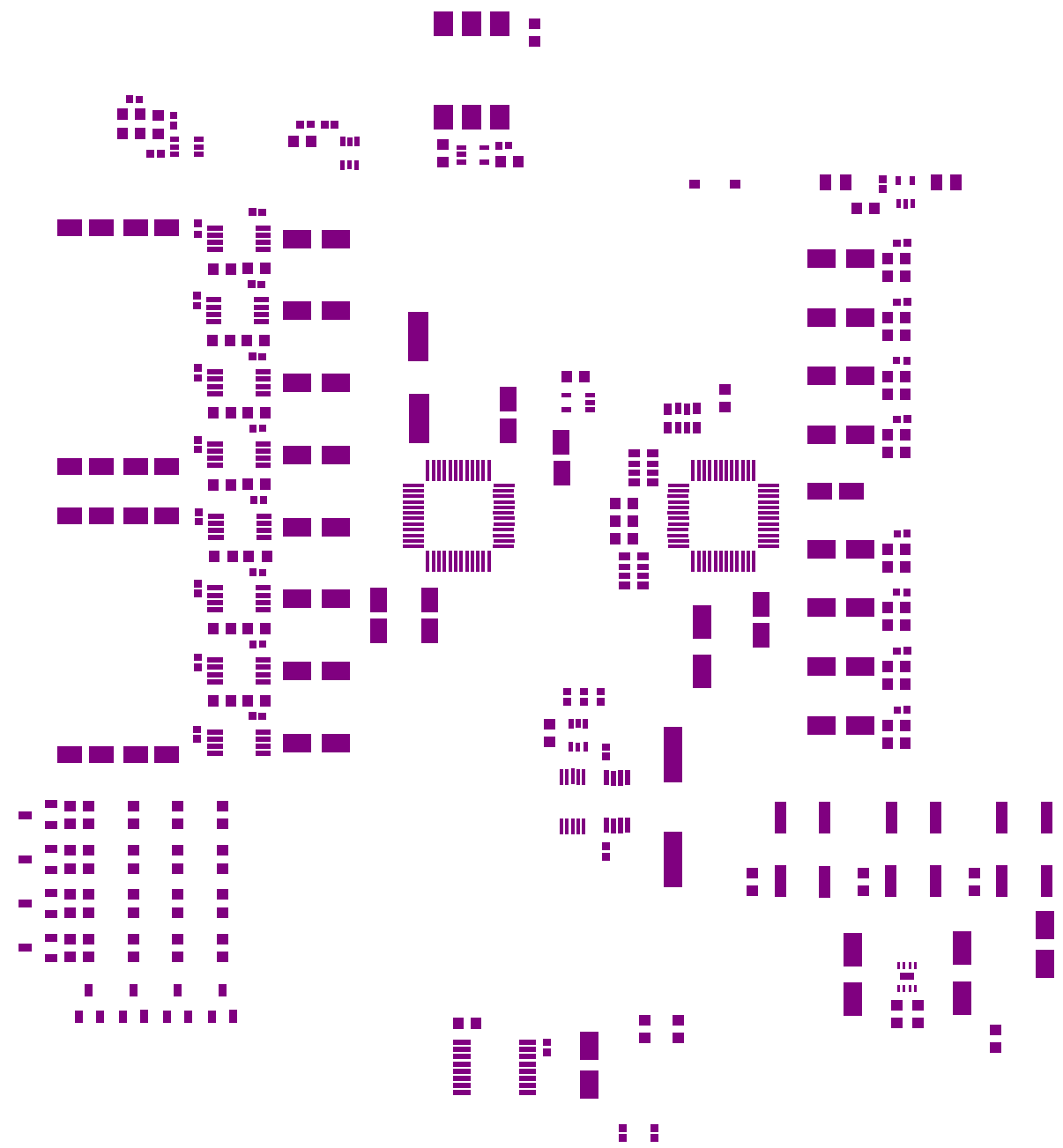
R33
R32
C32
R33
R43
R42
C43
R42
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C46
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C36
C37

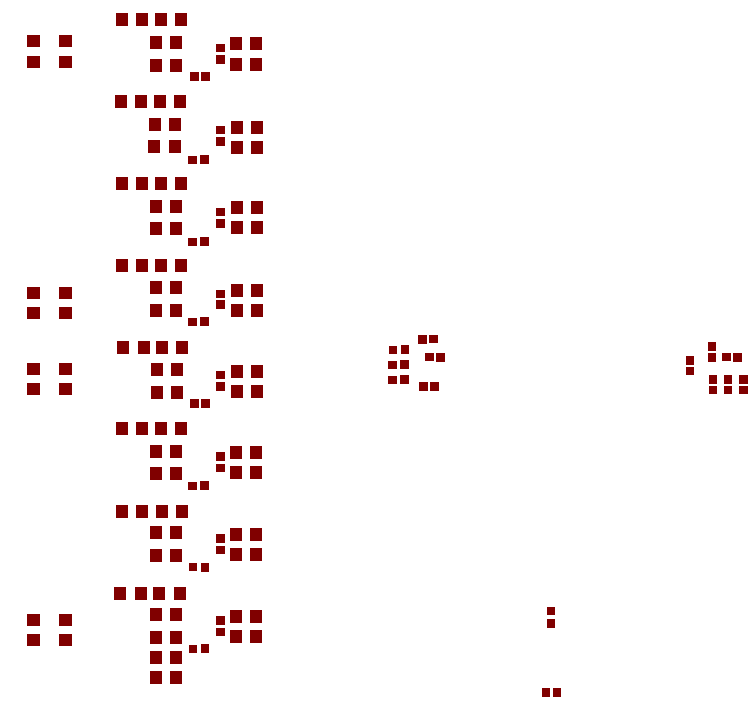
C63
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C71
C72



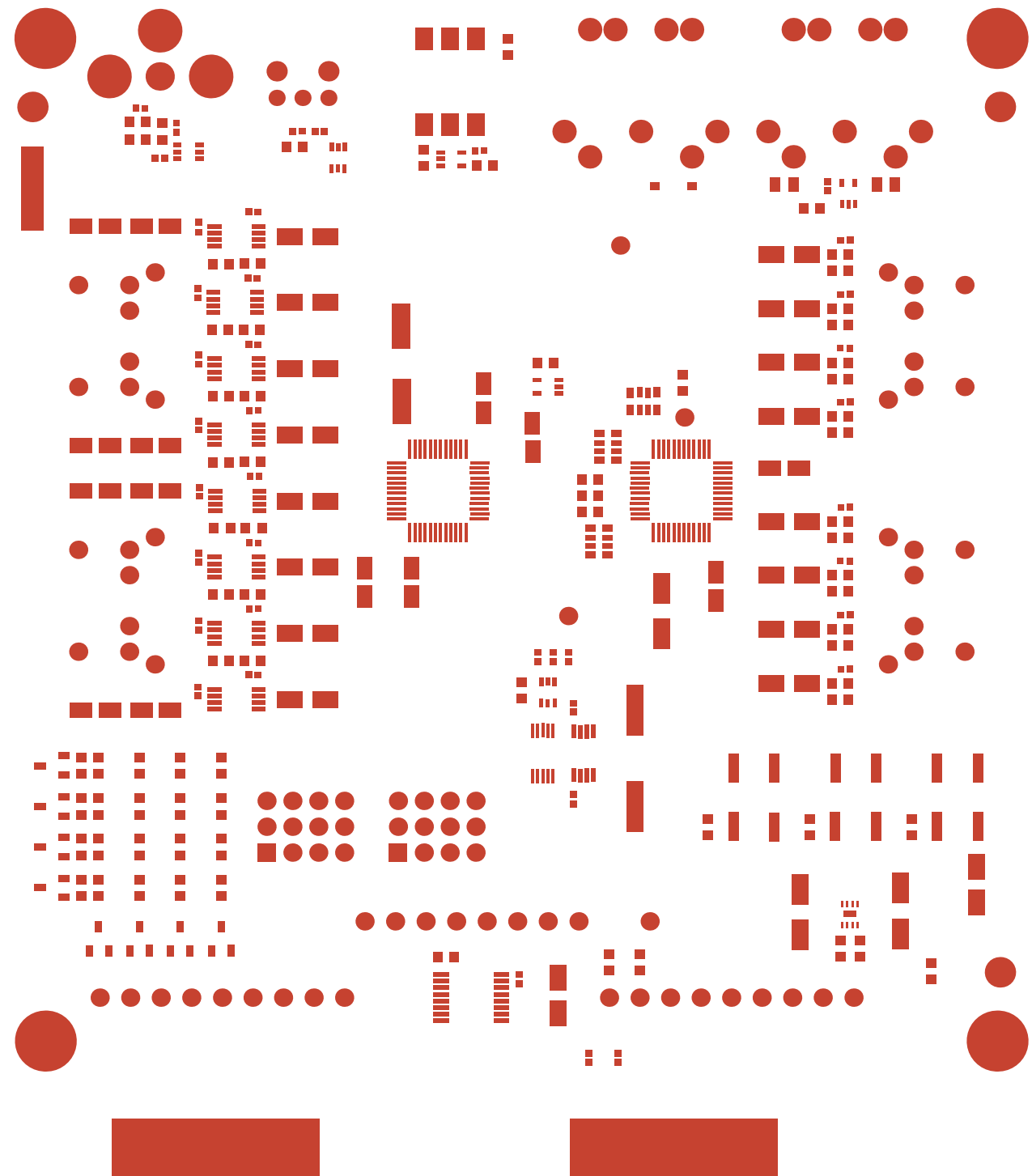
BOTTOM SILKSCREEN LAYER



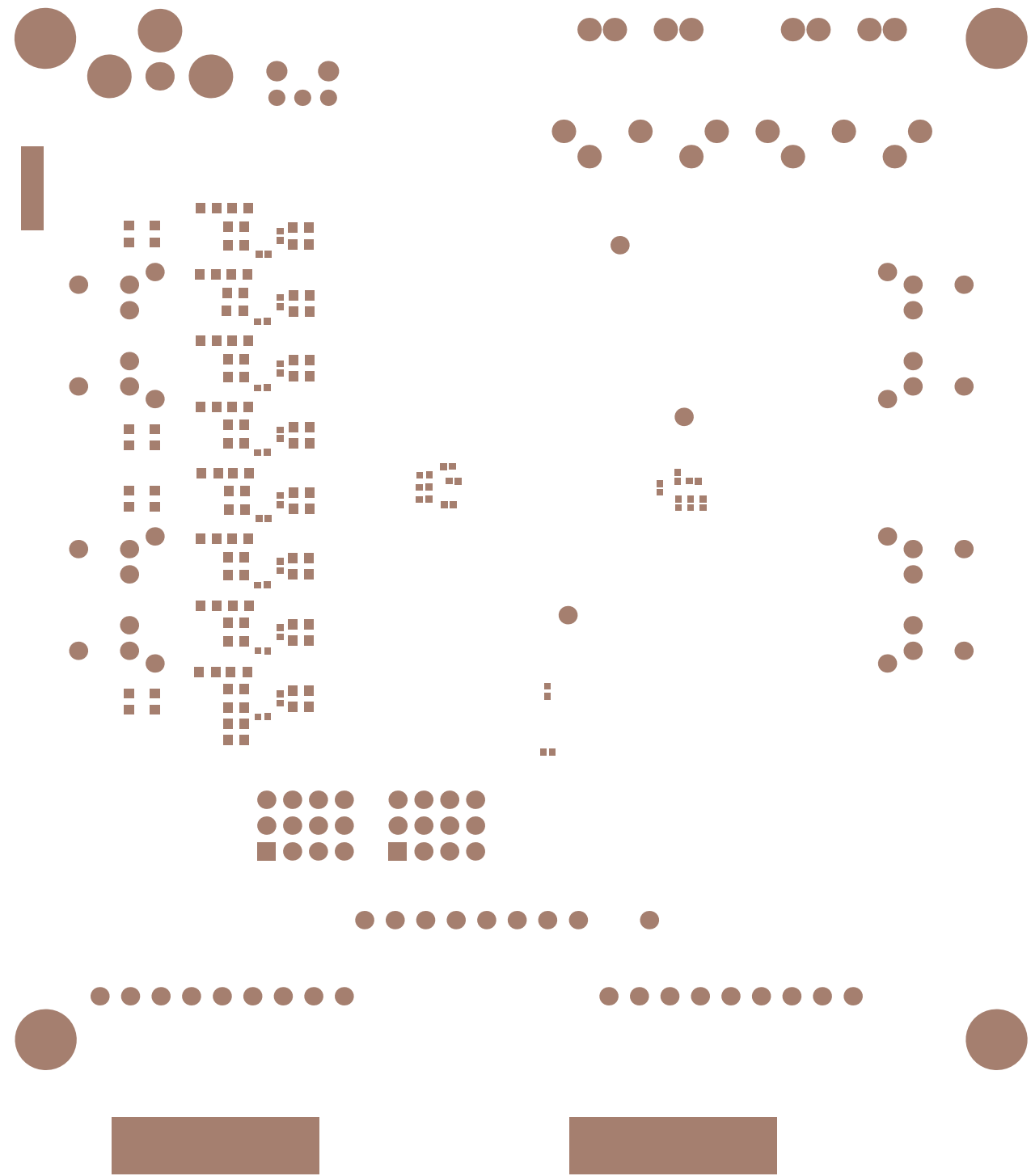
TOP PASTE LAYER



BOTTOM PASTE LAYER



TOP SOLDER MASK LAYER



BOTTOM SOLDER MASK LAYER

PCB Manufacturing Notes

General Info

Board dimensions – 115mm x 85mm
Number of layers – 4
Smallest hole – 0.3mm
Number of holes – Approx 660
Minimum Track & Gap – 0.20mm
RoHS/Lead Free – Yes
Material – FR4

Stackup

Stackup is to be as follows:

Layer	Copper Weight (Pre-Plating)
	0.5oz
	1oz
	1oz
	0.5oz

Finished board thickness to be 1.6mm, tolerance 0.1mm

Impedance Control

None required

Copper Thieving/Balancing

The supplier may add copper thieving/balancing if required.

Finish

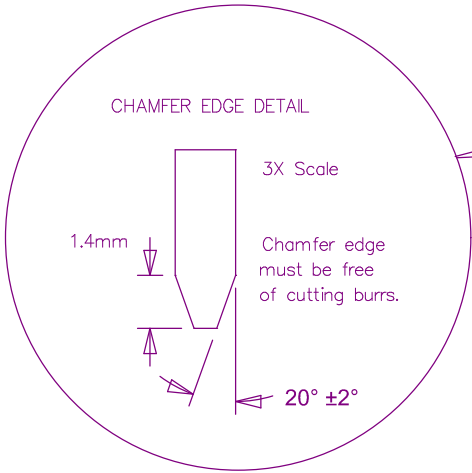
A.) Conductive finish
Plating to be immersion gold.

B.) Soldermask
Liquid photo imageable soldermask (GREEN). Pads have not been oversized.
Supplier should oversize soldermask on pads to suit process.

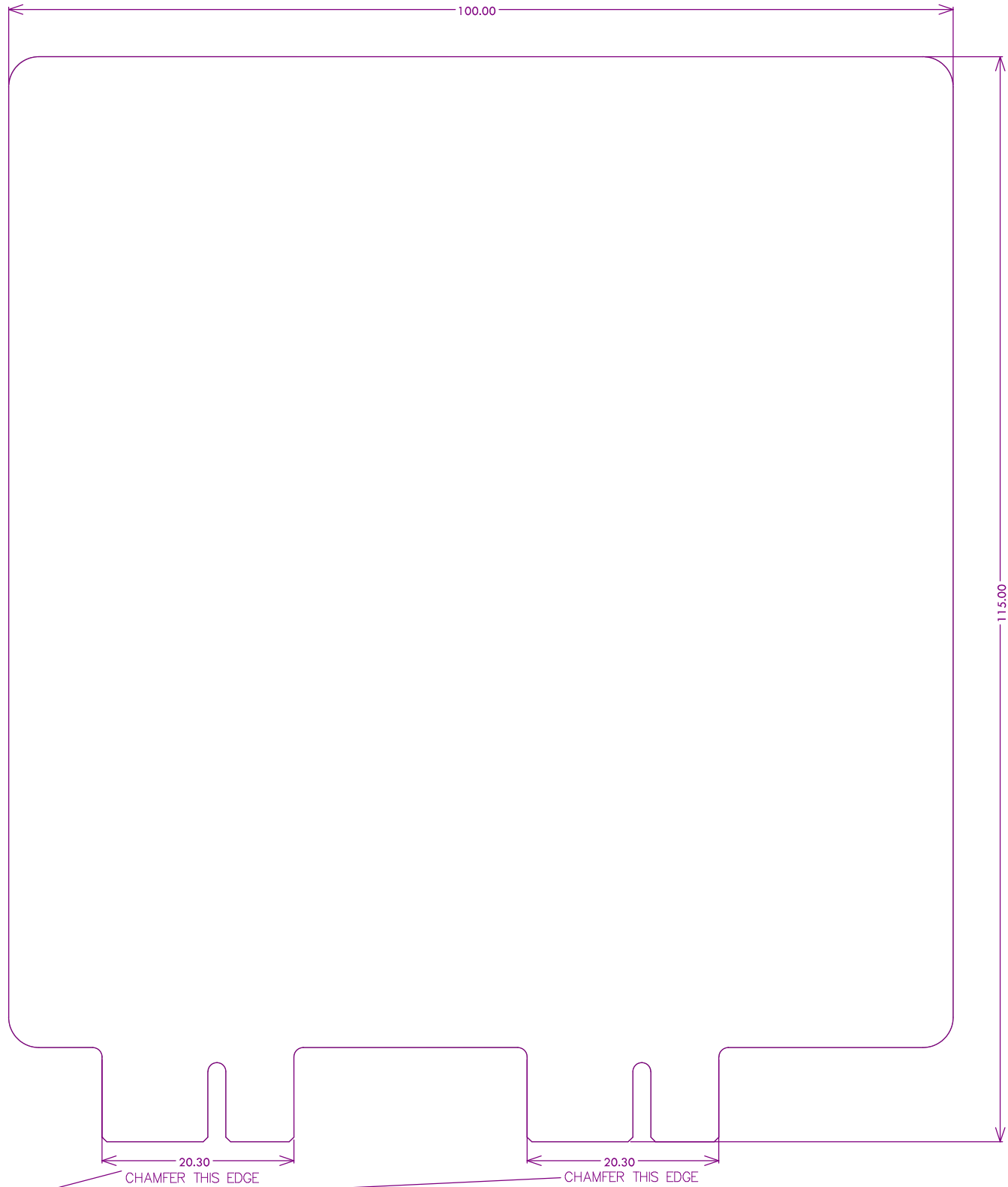
C.) Silkscreen
Colour white. Supplier should remove any silkscreen which overhangs pads.

Drill Data

Drill data is in Excellon format, metric (0000.000), no zero suppression, absolute coordinates.
Hole size is finished size.



FABRICATION INSTRUCTIONS



Project Name
XA-SK-AUDIO8

Sheet	Date	Revision
A4	MARCH 2014	1V2A

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B.) Soldermask

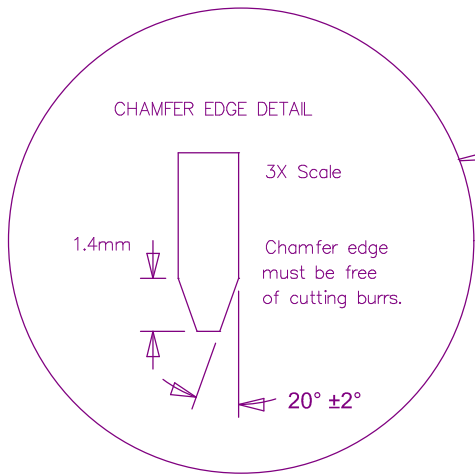
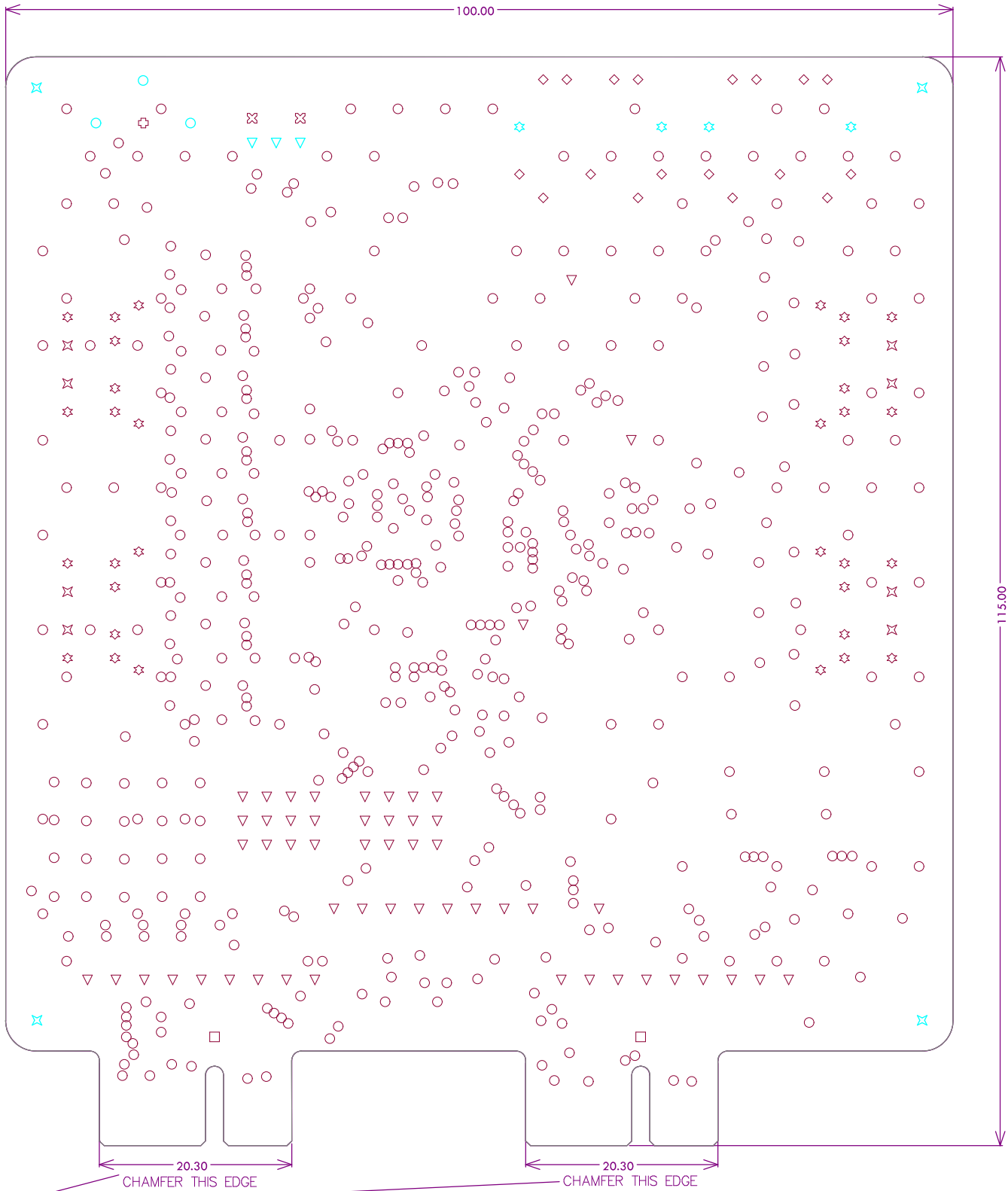
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FABRICATION INSTRUCTIONS DRILL DRAWING

Symbol	Hit Count	Tool Size	Plated	Hole Type
○	522	0.3mm (11.811mil)	PTH	Round
▽	3	0.8mm (31.496mil)	PTH	Round
▽	54	1mm (39.37mil)	PTH	Round
⊗	2	1.1mm (43.307mil)	NPTH	Round
✱	32	1.1mm (43.307mil)	PTH	Round
◇	18	1.4mm (55.118mil)	PTH	Round
⊕	1	1.7mm (66.929mil)	PTH	Round
⊗	8	2mm (78.74mil)	NPTH	Round
✱	4	2.4mm (94.488mil)	NPTH	Round
○	3	2.65mm (104.331mil)	PTH	Round
□	2	2.8mm (110.236mil)	NPTH	Round
⊗	4	3.2mm (125.984mil)	PTH	Round
	653 Total			

Drill Drawing.



Project Name
XA-SK-AUDIO8

Sheet	Date	Revision
A4	MARCH 2014	1V2A

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